



NOTE:

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCHES MIN. THICKNESS OVER NICKEL PLATED.
2. FLATNESS PERTAINS TO METALLIZED PADS ONLY.
3. LEAD TO LEAD LEAKAGE MUST NOT EXCEED  $10 \times 10^{-9}$  AMPS AT 100V D.C.
4. LEAD RESISTANCE : 0.5 OHM MAX.

△ 5. LEAD TIED DOWN TO DIE ATTACH PAD.

MARK	
⊗	ZERO GND
△	No. 34,35

MODIFICATIONS						NAME	48 LEAD CHIP CARRI (RC-48C)	TOLERANCES:		DRAWN	CHECKED	APPROVED	DATE
						SCALE	8 / 1	UNLESS OTHERWISE SPECIFIED		S.T	E.H		10.20.'76
△	ADEED: NOTE:5	09.12.'79	N.U	O.M		MATERIAL	KYOCERA A-473	±1% NLT ±.005					
△	REDRAWN :REDRAWN FOR DESIGN CHANGE	10.20.'76	S.T			THIRD ANGLE PROJECTION							
	CHANGE	DATE	DRAWN	CHECKED	APPROVED	<b>KYOCERA</b>	KYOCERA CORPORATION KYOTO JAPAN			DRAWING NO.	PB-61034-B		SHEET